

Highlights

Excellent Quality and Superior Service

- ▶ **Materials and Assembly Engineering expertise**
- ▶ **SMT assembly**
- ▶ **Flip Chip assembly**
- ▶ **Stacked die assembly**
- ▶ **BGA assembly**
- ▶ **Wirebonding**
 - Thermosonic Au and Ultrasonic Al
 - Reverse bond on ball
 - Au stud bump
- ▶ **Conformal coating**
- ▶ **Molded encapsulation**
- ▶ **Mil Std Certified**
- ▶ **QML listed**
- ▶ **Automated inspection**
- ▶ **Consigned or build-to-print BOM sourcing**

CORWIL offers a wide breadth of technologies for producing your most complex multichip and multi-component packaging (MCP). CORWIL has very experienced engineering and substrate design skills and we will help you select the bill of materials, the substrate types and the assembly methods. Whether you want to produce a SIP (System in Package), MCM (Multichip Module) or a stacked die assembly, our MCP team can handle your needs.

- Your module development starts with careful review and consultation by CORWIL's experienced engineers and designers. Together we select the optimum bill of materials and the optimum substrate design and type. Once the components, substrates, and fixtures are ready, CORWIL quickly assembles first articles for your test and evaluation. When approved, CORWIL will produce pre-production and production quantities.
- CORWIL has the wafer thinning and dicing, wire bonding, flip chip and SMT mounting and reflow, and encapsulation capacity to produce high volume production.
- CORWIL's SIP and MCP module production processes are highly flexible and cost effective to accommodate stacked die, multiple mounted planar die and components, rigid and flexible substrates, and molded encapsulation.

• Assembly Capabilities

- ▶ Class 1000 (cleanroom), Class 100 (laminarflow hoods)
- ▶ Wafer grind and polish (thinning to 50 microns of 100 to 200mm wafer diameters)
- ▶ Wafer sawing and dicing (100 to 300mm wafer diameters) (Si, GaAs, sapphire, SiGe, quartz, glass)
- ▶ Automated die inspection
- ▶ Epoxy and eutectic die attach
- ▶ Gold ball bonding on 45micron pitch (prototype), 50 micron (production), 35/70 micron staggered pad pitch
- ▶ Reverse wedge on ball bonding for stacked die
- ▶ Dam and fill, dispensed encapsulation (glob-top)
- ▶ Transfer mold encapsulation
- ▶ Flip chip inspection, placement and reflow (250 micron bump size, N2 environment)
- ▶ SMT stencil, place and reflow (N2 environment)
- ▶ Certified for Mil-Std-883 Class B or Class S
- ▶ ISO9001:2000 certified
- ▶ DSCC QML Listed
- ▶ No-lead and RoHS compliant assembly
- ▶ Quick-turn, including One-day turns available

- CORWIL has built its reputation providing customers with:
excellent quality and superior service

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ISO 9001:2000
FM38103

DSCC QML Listed
(Qualified Manufacturers List)
MIL-STD-883 DSCC Suitability